CY7C1461SV33-133AXC, CY7C1461SV33-133AXCT, CY7C1461SV33-133AXI

Last Updated: 07/27/2010

Bill of Materials	Assembly site G
Mold compound	KEG6000DA
Lead frame/Substrate	STW C7025 PPF
Lead finish/Solder ball	STW C7025 PPF
Die attach	QMI 509
Bonding wire	Nittetsu NT1
Die	Fab site A

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